



FLIP CHIP MODULES TEST SPECS

TYPE: R 203

TRIPLE FLIP-FLOP

TEST	CONDITIONS	MAXIMUM	MINIMUM
UPPER LEVEL	20MA LOAD TO -15 V	≤ 300 MV	
LOWER LEVEL	NO EXTERNAL LOAD	3.9 V	3.2 V
LOAD CURRENT	NO EXTERNAL LOAD	4.5 MA	3.7 MA
AC SENSITIVITY #1 GATE ENABLE GROUNDED. #2 GATE ALTERN. ENABLED.	HIGH FREQUENCY	+ 2.4 V	
	LOW FREQUENCY		+ 0.8 V
	HIGH FREQUENCY # 2	+ 2.5 V	
	DC DISABLE	- 2.5 V	
TTT	RISE	90 NS	
	FALL	130 NS	
MARGINS	+ 10V	+ 10 V	- 10 V
	- 15V	+ 3.0 V	3.0

TECHNICAL INFORMATION

Instruction literature and technical bulletins are available on all digital products, if you would like to be added to our mailing list for this type of material or if you have any questions about the equipment you have purchased, please contact the nearest Digital Sales Office.

MAINTENANCE INFORMATION

Repair of printed circuitry should be done with a low voltage, fairly cool soldering iron to prevent damage to the transistors and keep the copper from lifting. Oscilloscopes used to troubleshoot a module or system should be grounded to prevent damaging transients.

1/14/65